Theoretical Economics Letters

ISSN Online: 2162-2086

Special Issue on The Bond and Money Markets

Call for Papers

As money became a commodity, the money market became a component of the financial markets for assets involved in short-term borrowing, lending, buying and selling with original maturities of one year or less. Trading in the money markets is done over the counter and is wholesale. Money market trades in short-term financial instruments commonly called "paper". This contrasts with the capital market for longer-term funding, which is supplied by bonds and equity.

References to the "bond market" usually refer to the government bond market, because of its size, liquidity, relative lack of credit risk and, therefore, sensitivity to interest rates. Because of the inverse relationship between bond valuation and interest rates, the bond market is often used to indicate changes in interest rates or the shape of the yield curve. The yield curve is the measure of "cost of funding".

In this special issue, we intend to invite front-line researchers and authors to submit original researches and review articles on exploring **the bond and money markets**. Potential topics include, but are not limited to:

- Bond market
- Money markets
- Credit markets
- Financial markets
- Monetary policy
- Primary market
- Secondary market

Authors should read over the journal's <u>Authors' Guidelines</u> carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's <u>Paper Submission System</u>.

Please kindly notice that the "Special Issue" under your manuscript title is supposed to be specified and the research field "Special Issue - The Bond and Money Markets" should be chosen during your submission.

According to the following timetable:



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ISSN Online: 2162-2086

Manuscript Due	April 24th, 2014
Publication Date	June 2014

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